

Abstract of the Disclosure

Protective tape 22 is bonded onto the rear surface of a semiconductor element 1 prior to the resin sealing step, and then only the primary surface of the semiconductor element 1 is sealed with a resin layer 5 so that cracks and warping which would otherwise be caused by an external force or foreign matter at the rear surface of the semiconductor element was exposed, are prevented to facilitate the surface polishing step and also so that a lower profile is achieved for the semiconductor device by not sealing the rear surface with resin.